

ABSTRACT

[0046] Methods for dicing wafer stacks are provided. Preferably, the method includes the steps of: (1) providing a wafer stack having a first wafer and a second wafer; (2) exposing a portion of the first wafer by removing a portion of the second wafer; and (3) dicing the exposed portion of the first wafer such that a first die assembly is at least partially separated from the wafer stack. Wafer stacks and die assemblies also are provided.

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